



BT152-500RT

SCR

Rev. 2 — 9 June 2011

Product data sheet

1. Product profile

1.1 General description

Planar passivated Silicon Controlled Rectifier in a SOT78 (TO-220AB) plastic package intended for use in applications requiring very high inrush current capability, high junction temperature capability and high thermal cycling performance.

1.2 Features and benefits

- High junction temperature capability
- High thermal cycling performance
- Planar passivated for voltage ruggedness and reliability
- Very high current surge capability

1.3 Applications

- Ignition circuits
- Motor control
- Protection circuits e.g. SMPS inrush current
- Voltage regulation

1.4 Quick reference data

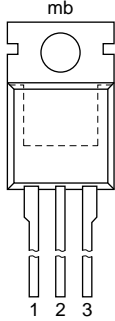

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{DRM}	repetitive peak off-state voltage		-	-	500	V
V_{RRM}	repetitive peak reverse voltage		-	-	500	V
I_{TSM}	non-repetitive peak on-state current	half sine wave; $T_{j(\text{init})} = 25\text{ °C}$; $t_p = 8.3\text{ ms}$	-	-	220	A
		half sine wave; $T_{j(\text{init})} = 25\text{ °C}$; $t_p = 10\text{ ms}$; see Figure 4 ; see Figure 5	-	-	200	A
$I_{T(AV)}$	average on-state current	half sine wave; $T_{mb} \leq 122\text{ °C}$; see Figure 3	-	-	13	A
$I_{T(RMS)}$	RMS on-state current	half sine wave; see Figure 1 ; see Figure 2	-	-	20	A
Static characteristics						
I_{GT}	gate trigger current	$V_D = 12\text{ V}$; $I_T = 100\text{ mA}$; $T_j = 25\text{ °C}$; see Figure 7	-	3	32	mA



2. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode		
2	A	anode		
3	G	gate		
mb	A	mounting base; connected to anode		

SOT78 (TO-220AB)

3. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
BT152-500RT	TO-220AB	plastic single-ended package; heatsink mounted; 1 mounting hole; 3-lead TO-220AB	SOT78

4. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{DRM}	repetitive peak off-state voltage		-	500	V
V_{RRM}	repetitive peak reverse voltage		-	500	V
$I_{T(AV)}$	average on-state current	half sine wave; $T_{mb} \leq 122$ °C; see Figure 3	-	13	A
$I_{T(RMS)}$	RMS on-state current	half sine wave; see Figure 1 ; see Figure 2	-	20	A
I_{TSM}	non-repetitive peak on-state current	half sine wave; $T_{j(init)} = 25$ °C; $t_p = 8.3$ ms	-	220	A
		half sine wave; $T_{j(init)} = 25$ °C; $t_p = 10$ ms; see Figure 4 ; see Figure 5	-	200	A
I^2t	I^2t for fusing	$t_p = 10$ ms; sine-wave pulse	-	200	A ² s
di_T/dt	rate of rise of on-state current	$I_T = 50$ A; $I_G = 200$ mA; $di_G/dt = 200$ mA/ μ s	-	200	A/ μ s
I_{GM}	peak gate current		-	5	A
V_{RGM}	peak reverse gate voltage		-	5	V
P_{GM}	peak gate power		-	20	W
$P_{G(AV)}$	average gate power	over any 20 ms period	-	1	W
T_{stg}	storage temperature		-40	150	°C
T_j	junction temperature		-	150	°C

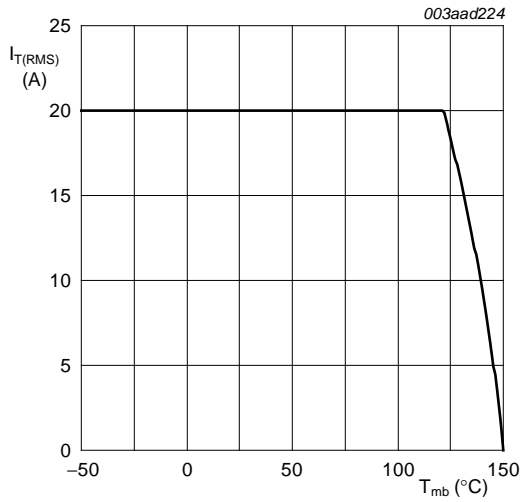
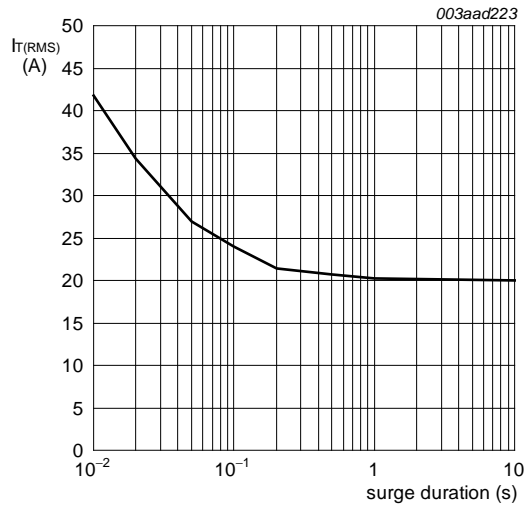
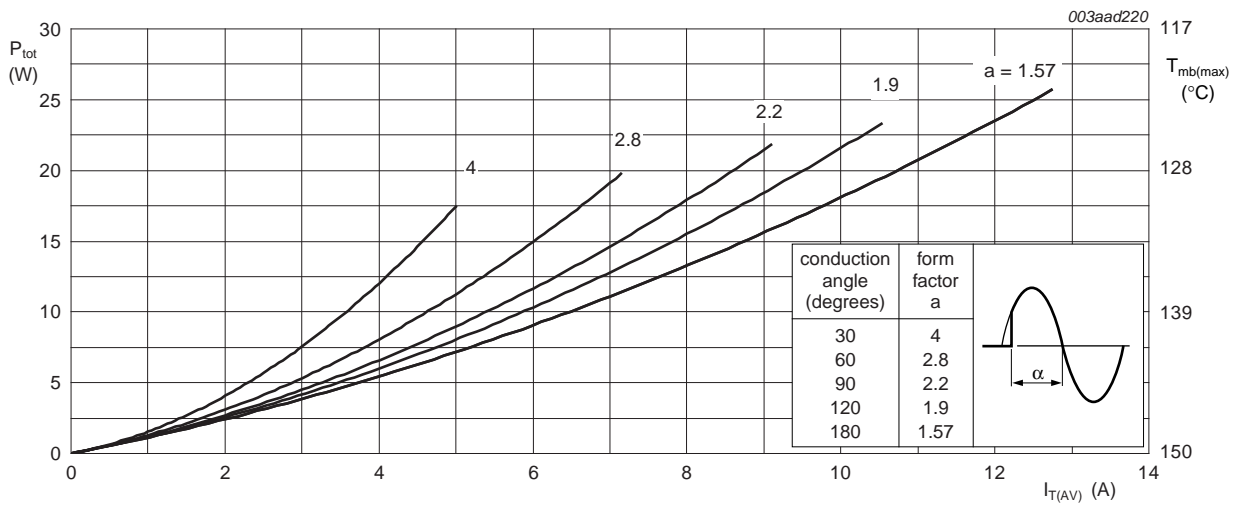


Fig 1. RMS on-state current as a function of mounting base temperature; maximum values



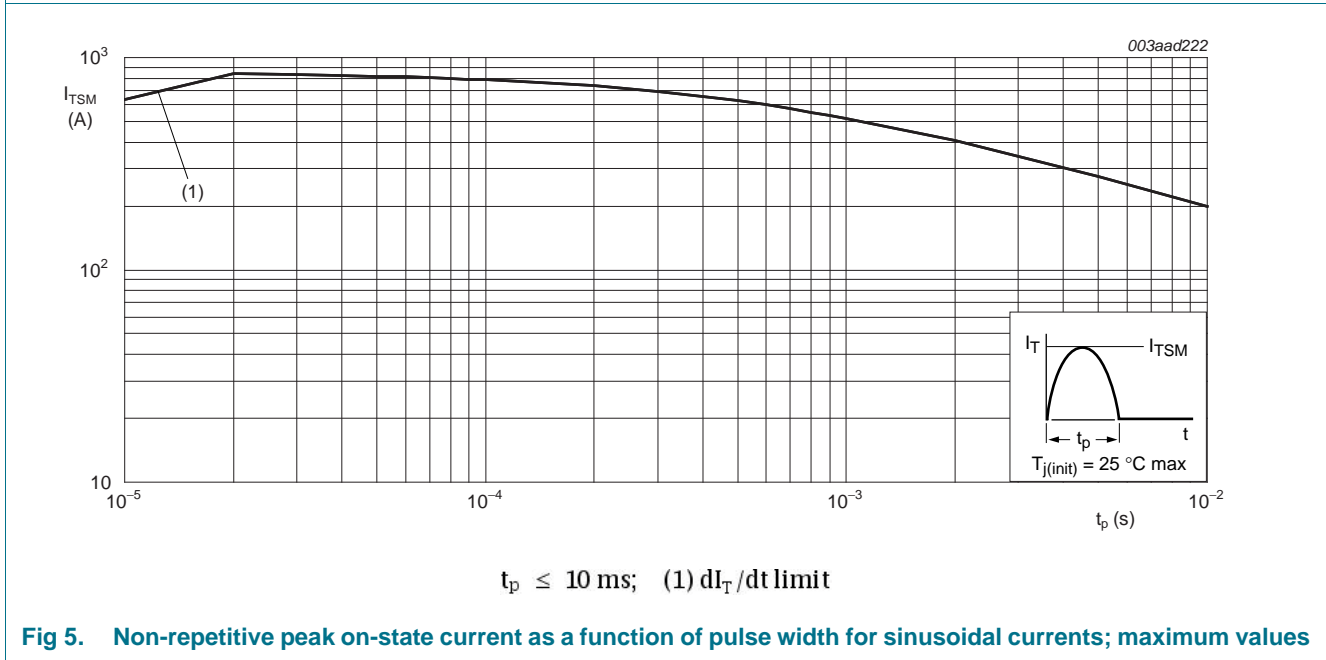
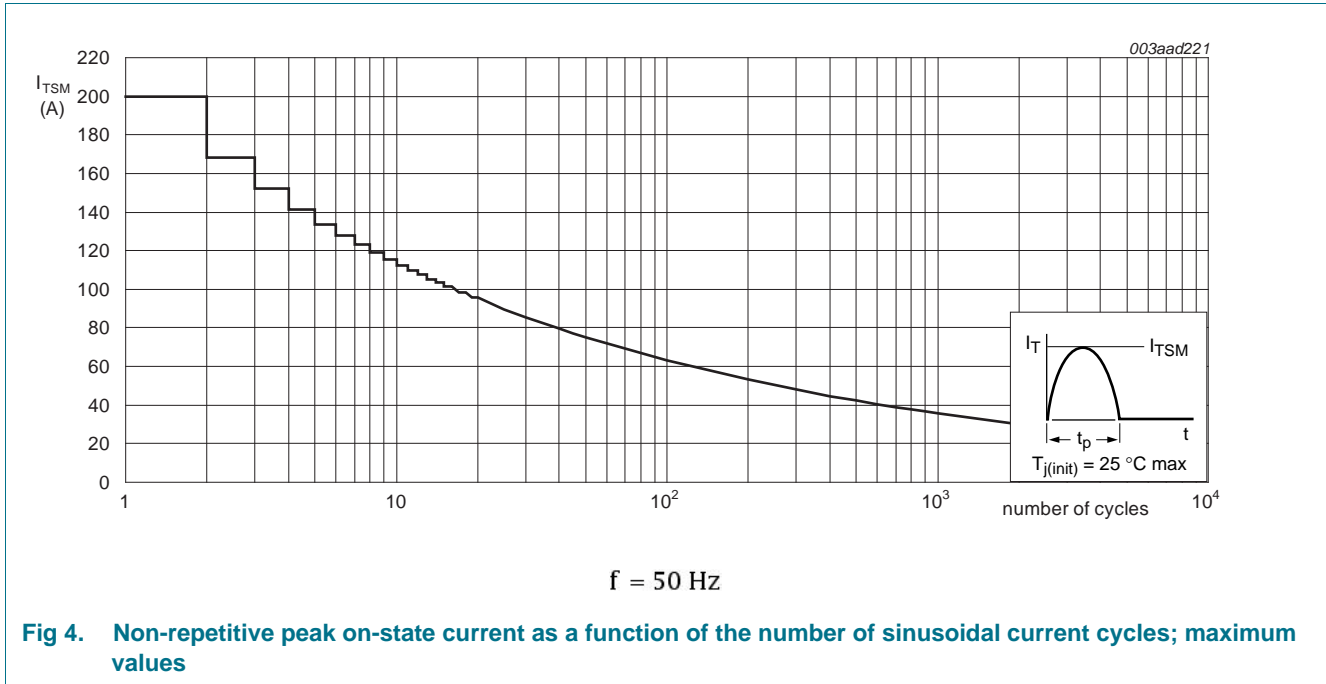
f = 50 Hz; T_{mb} = 122 °C

Fig 2. RMS on-state current as a function of surge duration; maximum values



$$a = \text{form factor} = I_{T(RMS)} / I_{T(AV)}$$

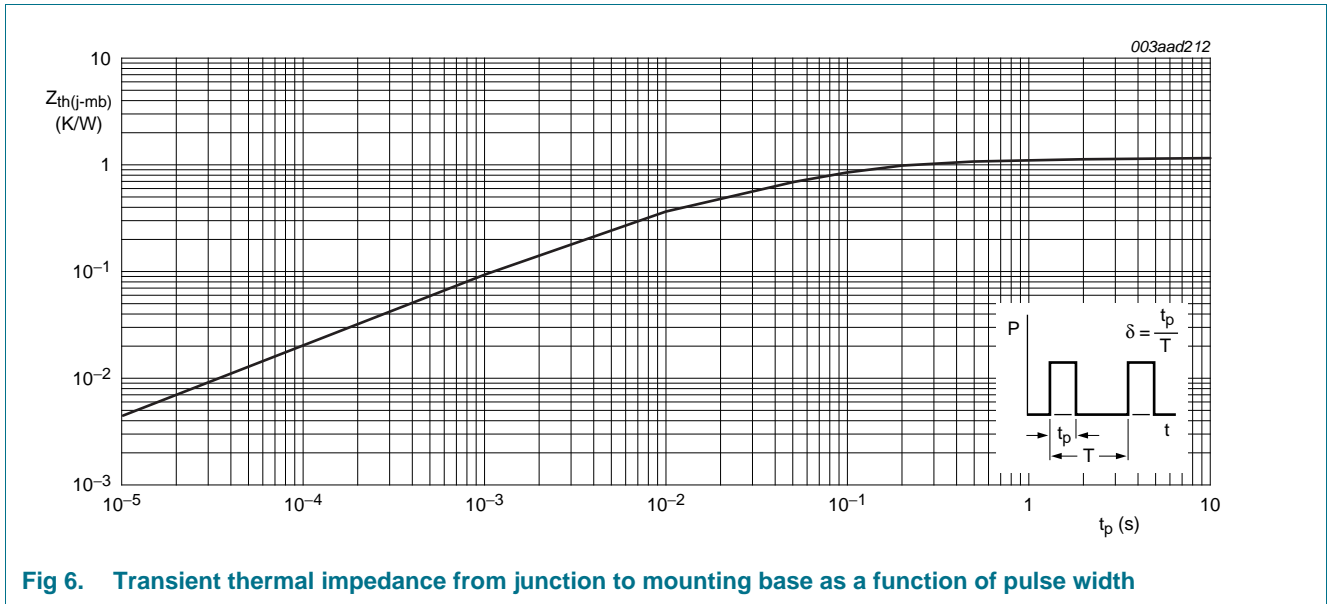
Fig 3. Total power dissipation as a function of average on-state current; maximum values



5. Thermal characteristics

Table 5. Thermal characteristics

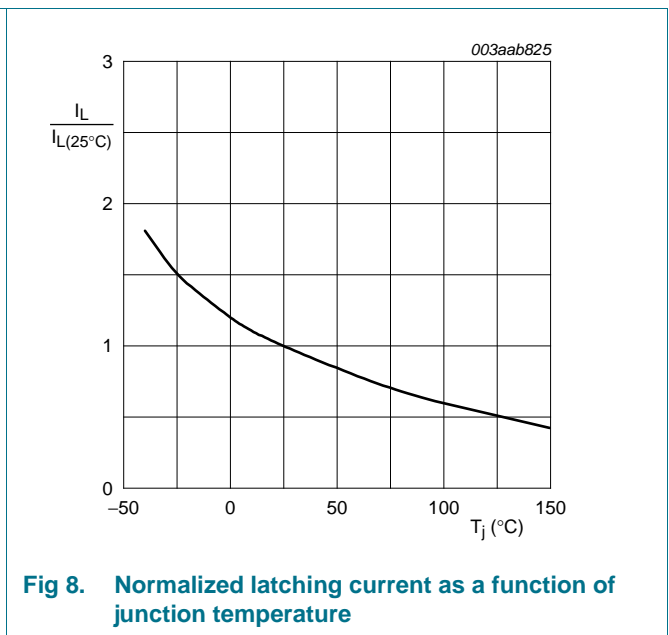
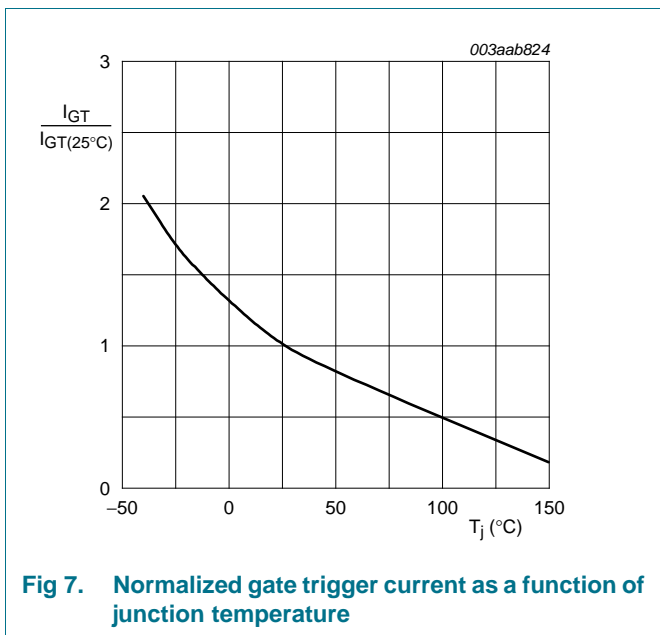
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	see Figure 6	-	-	1.1	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient free air	in free air	-	60	-	K/W



6. Characteristics

Table 6. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static characteristics						
I_{GT}	gate trigger current	$V_D = 12\text{ V}; I_T = 100\text{ mA}; T_j = 25\text{ }^\circ\text{C}$; see Figure 7	-	3	32	mA
I_L	latching current	$V_D = 12\text{ V}; I_G = 100\text{ mA}; T_j = 25\text{ }^\circ\text{C}$; see Figure 8	-	25	80	mA
I_H	holding current	$T_j = 25\text{ }^\circ\text{C}$; see Figure 9	-	15	60	mA
V_T	on-state voltage	$I_T = 40\text{ A}; T_j = 25\text{ }^\circ\text{C}$; see Figure 10	-	1.4	1.75	V
V_{GT}	gate trigger voltage	$V_D = 12\text{ V}; I_T = 100\text{ mA}; T_j = 25\text{ }^\circ\text{C}$; see Figure 11	-	0.6	1.5	V
		$V_D = 500\text{ V}; I_T = 100\text{ mA}; T_j = 125\text{ }^\circ\text{C}$; see Figure 11	0.25	0.4	-	V
I_D	off-state current	$V_D = 500\text{ V}; T_j = 125\text{ }^\circ\text{C}$	-	0.2	1	mA
I_R	reverse current	$T_j = 125\text{ }^\circ\text{C}; V_R = 500\text{ V}$	-	0.2	1	mA
Dynamic characteristics						
dV_D/dt	rate of rise of off-state voltage	$V_{DM} = 335\text{ V}; T_j = 125\text{ }^\circ\text{C}$; exponential waveform; gate open circuit; see Figure 12	200	300	-	V/ μs
t_{gt}	gate-controlled turn-on time	$I_{TM} = 40\text{ A}; V_D = 500\text{ V}; I_G = 100\text{ mA}; dI_G/dt = 5\text{ A}/\mu\text{s}$	-	2	-	μs
t_q	commutated turn-off time	$V_{DM} = 335\text{ V}; T_j = 125\text{ }^\circ\text{C}; I_{TM} = 20\text{ A}; V_R = 25\text{ V}; (dI_T/dt)_M = 30\text{ A}/\mu\text{s}; dV_D/dt = 50\text{ V}/\mu\text{s}; R_{GK} = 100\text{ }\Omega$	-	70	-	μs



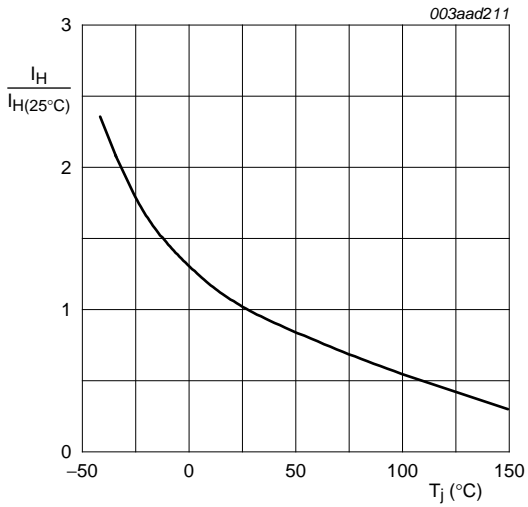
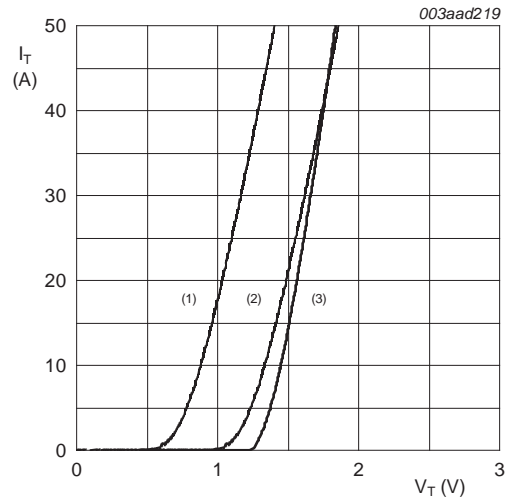


Fig 9. Normalized holding current as a function of junction temperature



$V_o = 1.06\text{ V}; R_s = 0.03\ \Omega$

- (1) $T_j = 150\text{ }^\circ\text{C}$; typical values
- (2) $T_j = 150\text{ }^\circ\text{C}$; maximum values
- (3) $T_j = 25\text{ }^\circ\text{C}$; maximum values

Fig 10. On-state current as a function of on-state voltage

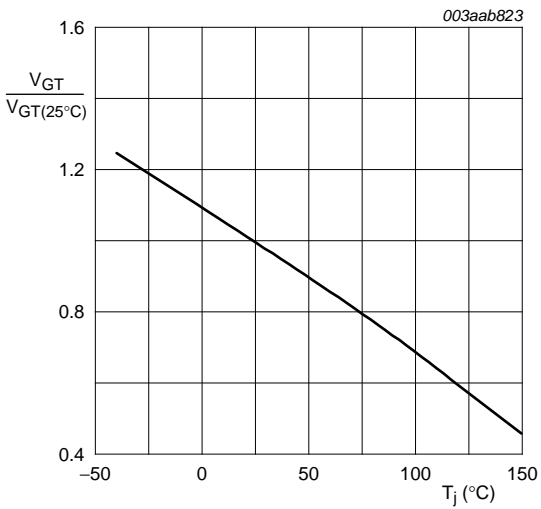
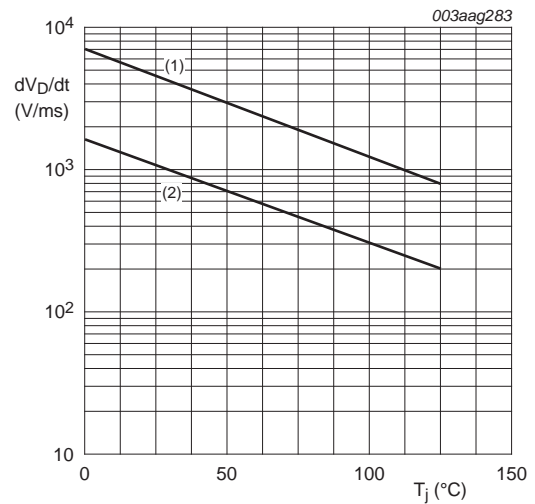


Fig 11. Normalized gate trigger voltage as a function of junction temperature



- (1) $R_{GK} = 100\ \Omega$
- (2) Gate open circuit

Fig 12. Critical rate of rise of off-state voltage as a function of junction temperature; typical values

7. Package outline

Plastic single-ended package; heatsink mounted; 1 mounting hole; 3-lead TO-220AB

SOT78

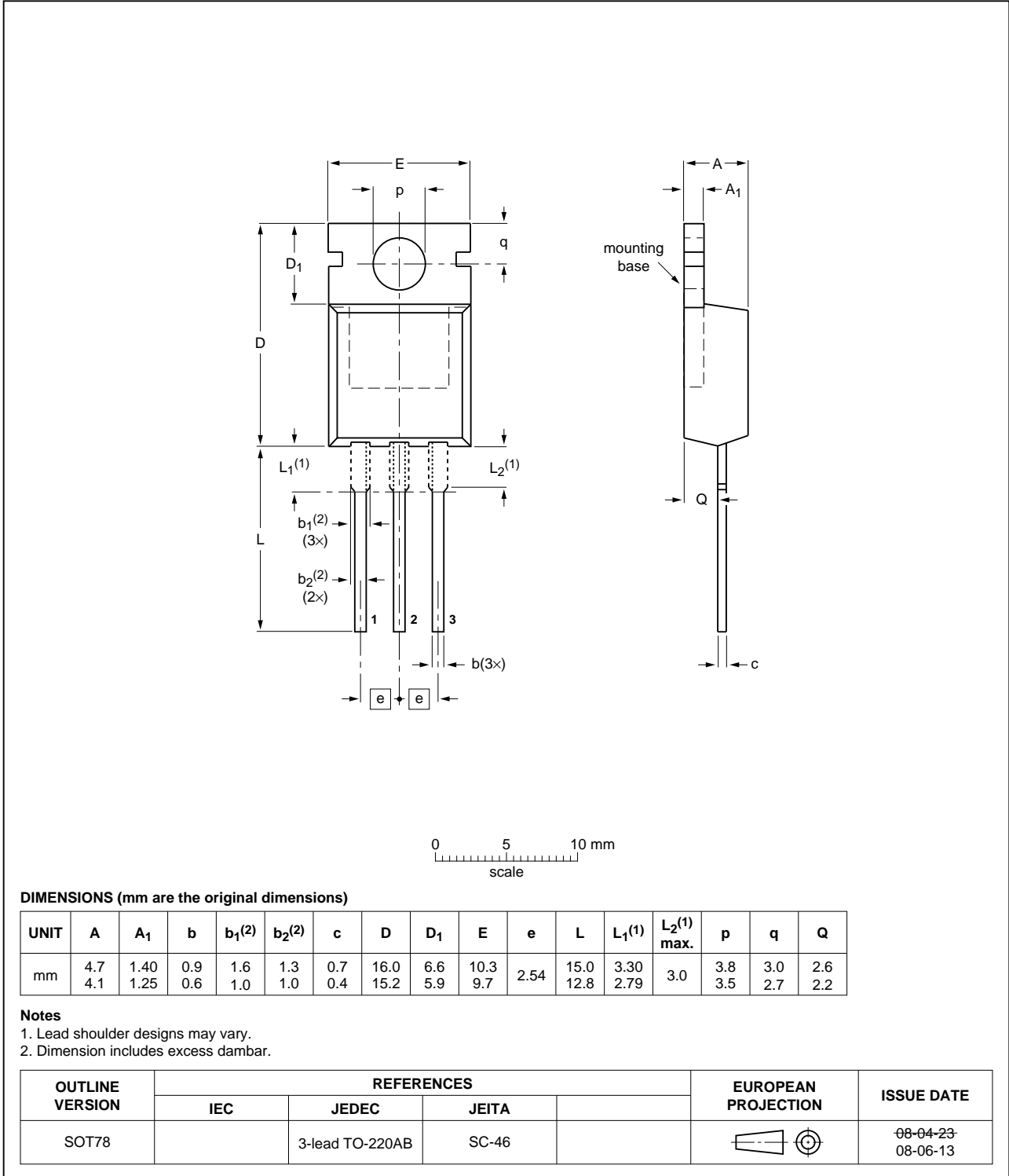


Fig 13. Package outline SOT78 (TO-220AB)

8. Revision history

Table 7. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BT152-500RT v.2	20110609	Product data sheet	-	BT152-500RT v.1
Modifications:	• Various changes to content.			
BT152-500RT v.1	20090512	Product data sheet	-	-

9. Legal information

9.1 Data sheet status

Document status ^[1] ^[2]	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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Product [short] data sheet	Production	This document contains the product specification.

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